



21NM65

Power MOSFET

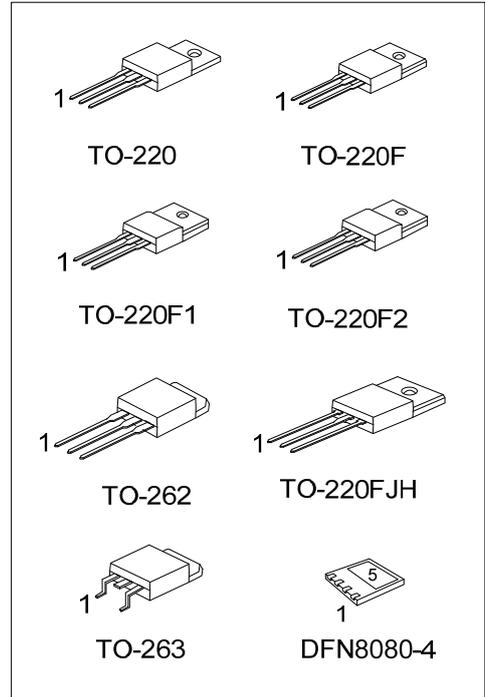
21A, 650V N-CHANNEL POWER MOSFET

DESCRIPTION

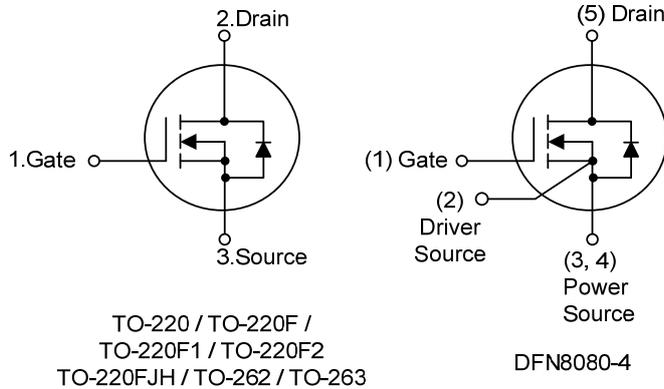
The **UTC 21NM65** is a Super Junction MOSFET Structure and is designed to have better characteristics, such as fast switching time, low gate charge, low on-state resistance and a high rugged avalanche characteristics. This power MOSFET is usually used at AC-DC converters for power applications.

FEATURES

- * $R_{DS(ON)} \leq 0.22 \Omega @ V_{GS}=10V, I_D=10.5A$
- * High Switching Speed
- * 100% Avalanche Tested



SYMBOL



■ ABSOLUTE MAXIMUM RATINGS ($T_C=25^\circ\text{C}$, unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		V_{DSS}	650	V
Gate-Source Voltage		V_{GSS}	± 30	V
Drain Current	Continuous	I_D	21	A
	Pulsed (Note 2)	I_{DM}	42	A
Avalanche Energy	Single Pulsed (Note 3)	E_{AS}	122	mJ
Peak Diode Recovery dv/dt (Note 4)		dv/dt	8.4	V/ns
Power Dissipation	TO-220/TO-262 TO-263	P_D	125	W
	TO-220F/TO-220F1 TO-220F2/TO-220FJH		34	W
	DFN8080-4		30	W
Junction Temperature		T_J	+150	$^\circ\text{C}$
Storage Temperature		T_{STG}	-55 ~ +150	$^\circ\text{C}$

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

2. Repetitive Rating: Pulse width limited by maximum junction temperature.

3. $L = 9.0\text{mH}$, $I_{AS} = 5.2\text{A}$, $V_{DD} = 50\text{V}$, $R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$

4. $I_{SD} \leq 21\text{A}$, $di/dt \leq 200\text{A}/\mu\text{s}$, $V_{DD} \leq BV_{DSS}$, Starting $T_J = 25^\circ\text{C}$

■ THERMAL DATA

PARAMETER		SYMBOL	RATINGS	UNIT
Junction to Ambient	TO-220/TO-220F TO-220F1/TO-220F2 TO-220FJH/TO-262 TO-263	θ_{JA}	62.5	$^\circ\text{C}/\text{W}$
	DFN8080-4		30 (Note)	$^\circ\text{C}/\text{W}$
Junction to Case	TO-220/TO-262 TO-263	θ_{JC}	1	$^\circ\text{C}/\text{W}$
	TO-220F/TO-220F1 TO-220F2/TO-220FJH		3.67	$^\circ\text{C}/\text{W}$
	DFN8080-4		1.92 (Note)	$^\circ\text{C}/\text{W}$

Note: Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

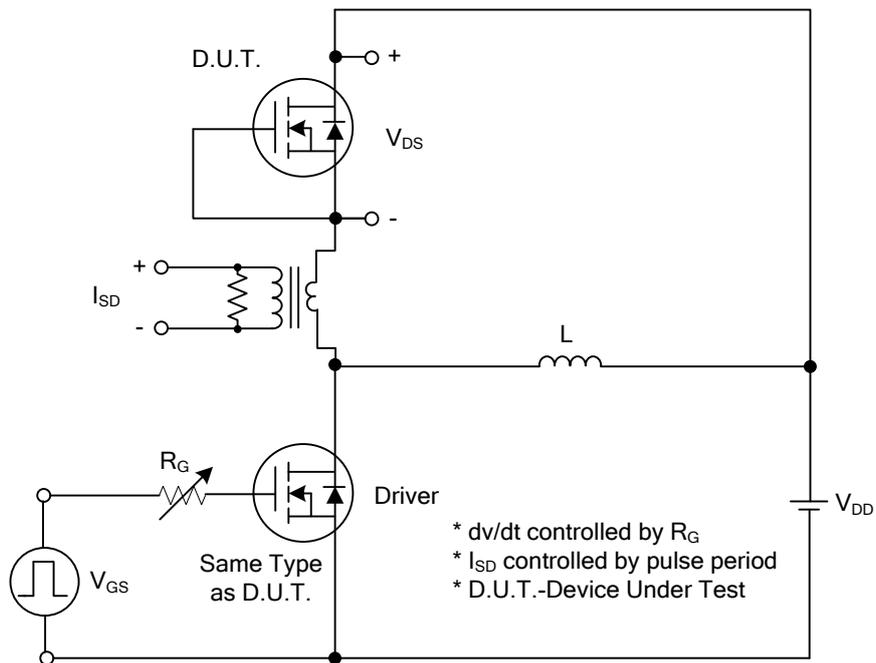
■ ELECTRICAL CHARACTERISTICS ($T_J=25^\circ\text{C}$, unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage	BV_{DSS}	$I_D=250\mu\text{A}$, $V_{GS}=0\text{V}$	650			V	
Drain-Source Leakage Current	I_{DSS}	$V_{DS}=650\text{V}$, $V_{GS}=0\text{V}$			10	μA	
Gate- Source Leakage Current	Forward	I_{GSS}			+100	nA	
	Reverse				-100	nA	
ON CHARACTERISTICS							
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}$, $I_D=250\mu\text{A}$	2.5		4.5	V	
Static Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=10\text{V}$, $I_D=10.5\text{A}$			0.22	Ω	
DYNAMIC PARAMETERS							
Input Capacitance	C_{ISS}	$V_{GS}=0\text{V}$, $V_{DS}=50\text{V}$, $f=1.0\text{MHz}$		1500		pF	
Output Capacitance	C_{OSS}				130		pF
Reverse Transfer Capacitance	C_{RSS}				3.6		pF
SWITCHING PARAMETERS							
Total Gate Charge	Q_G	$V_{DS}=520\text{V}$, $V_{GS}=10\text{V}$, $I_D=21\text{A}$ (Note 1, 2)		52		nC	
Gate to Source Charge	Q_{GS}				8		nC
Gate to Drain Charge	Q_{GD}				18		nC
Turn-ON Delay Time	$t_{D(ON)}$	$V_{DS}=100\text{V}$, $V_{GS}=10\text{V}$, $I_D=15\text{A}$, $R_G=25\Omega$ (Note 1, 2)		26		ns	
Rise Time	t_R				26		ns
Turn-OFF Delay Time	$t_{D(OFF)}$				220		ns
Fall-Time	t_F				80		ns
SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS							
Maximum Body-Diode Continuous Current	I_S				21	A	
Maximum Body-Diode Pulsed Current	I_{SM}				42	A	
Drain-Source Diode Forward Voltage	V_{SD}	$I_S=21\text{A}$, $V_{GS}=0\text{V}$			1.4	V	
Body Diode Reverse Recovery Time	t_{rr}	$I_S=21\text{A}$, $V_{GS}=0\text{V}$,		470		ns	
Body Diode Reverse Recovery Charge	Q_{rr}	$di_F/dt=100\text{A}/\mu\text{s}$ (Note 1)		8.6		μC	

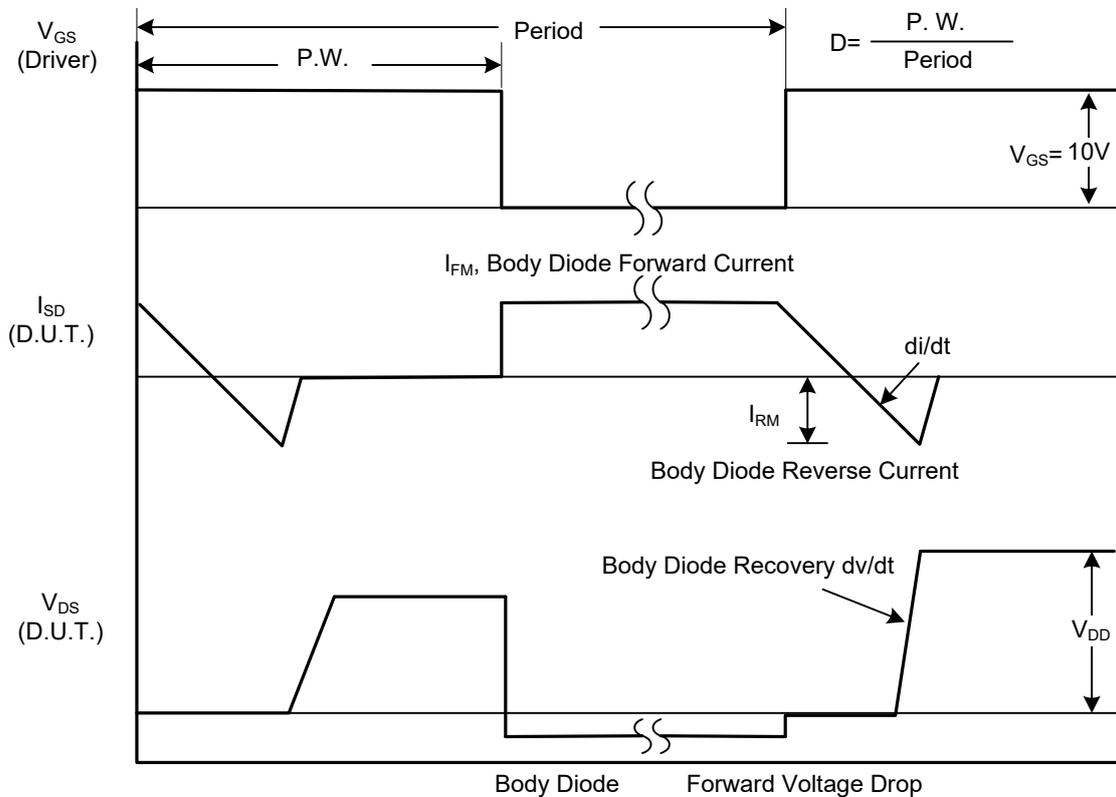
Notes: 1. Pulse Test: Pulse width $\leq 300\mu\text{s}$, Duty cycle $\leq 2\%$.

2. Essentially independent of operating ambient temperature.

TEST CIRCUITS AND WAVEFORMS



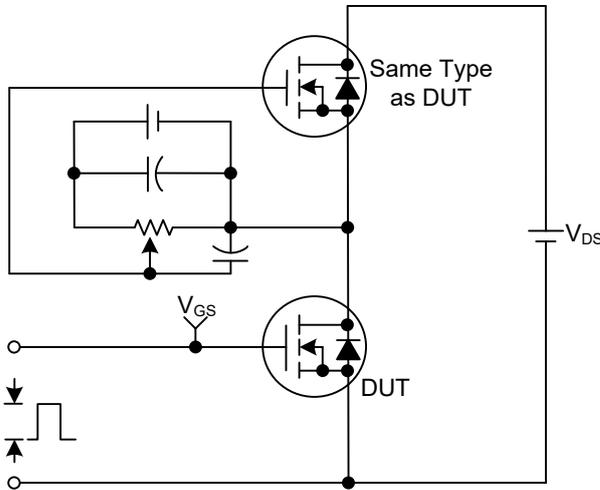
Peak Diode Recovery dv/dt Test Circuit



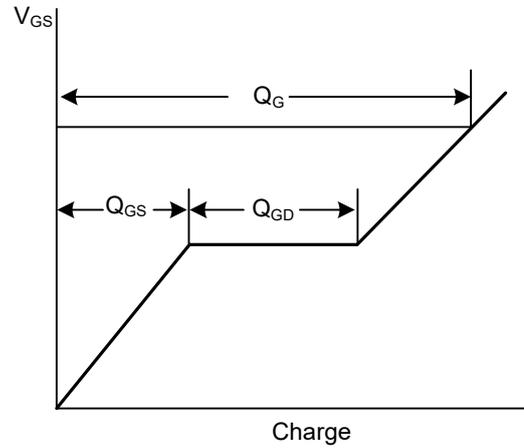
Peak Diode Recovery dv/dt Waveforms

■ TEST CIRCUITS AND WAVEFORMS

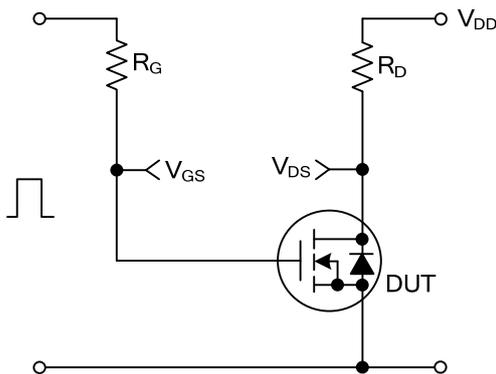
Gate Charge Test Circuit



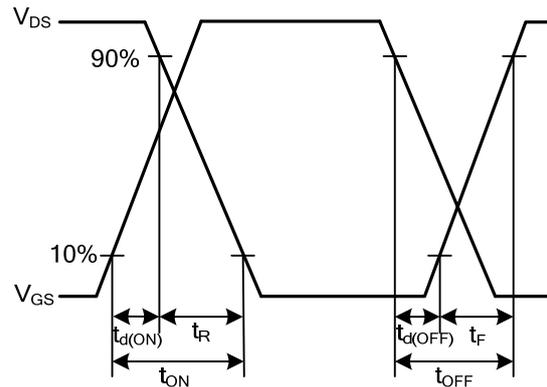
Gate Charge Waveforms



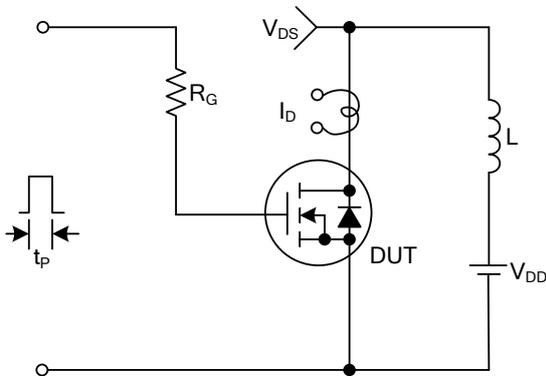
Resistive Switching Test Circuit



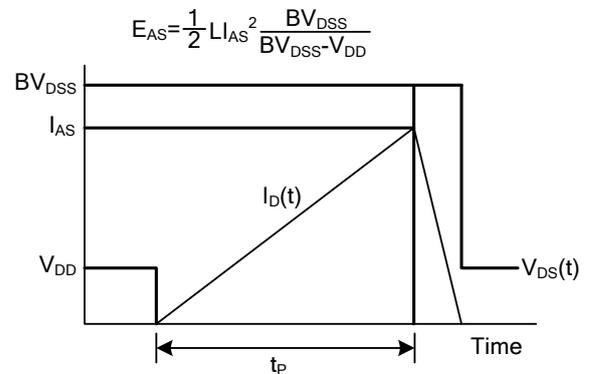
Resistive Switching Waveforms



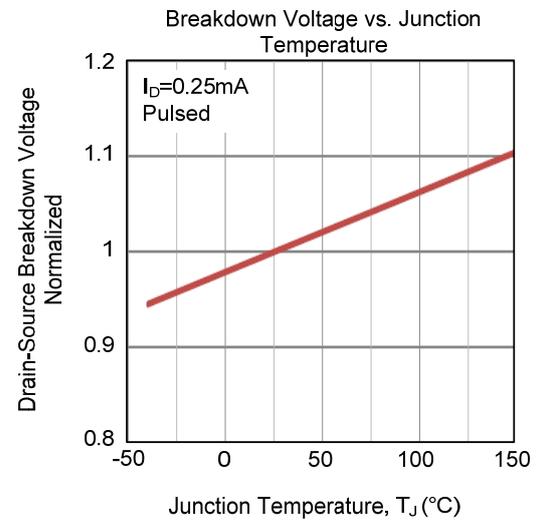
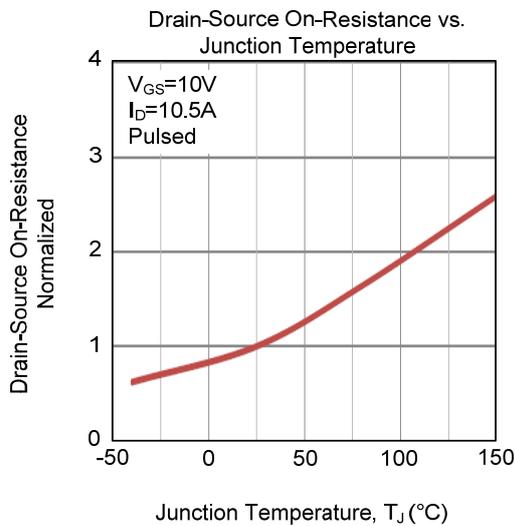
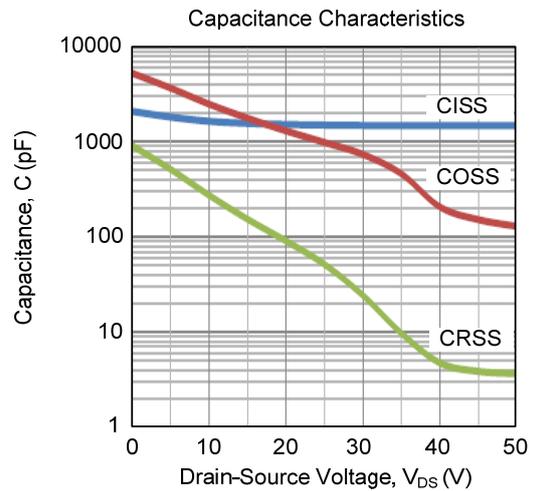
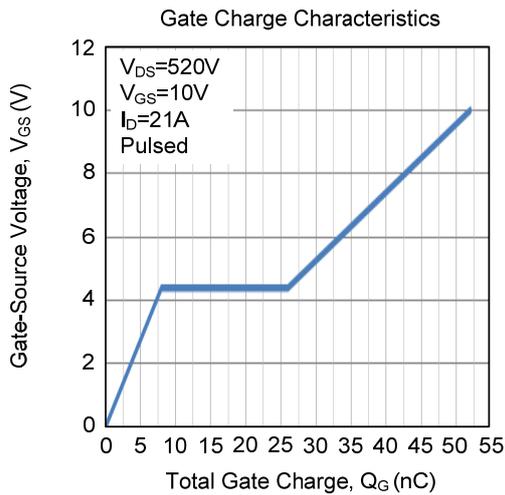
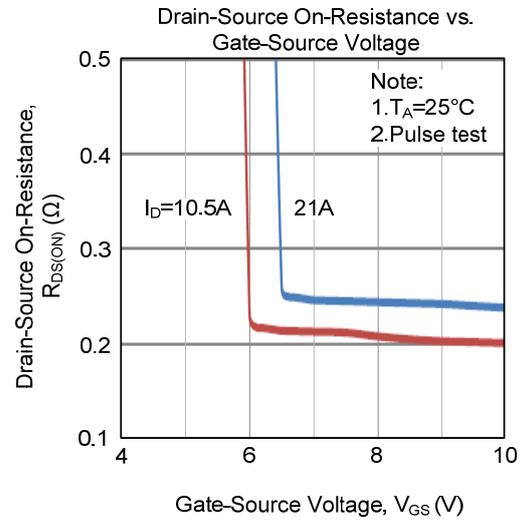
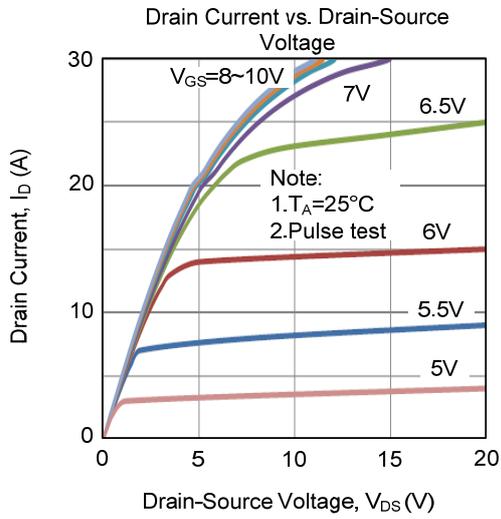
Unclamped Inductive Switching Test Circuit



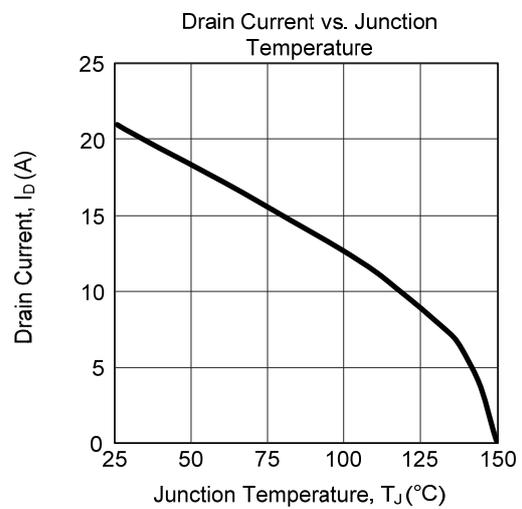
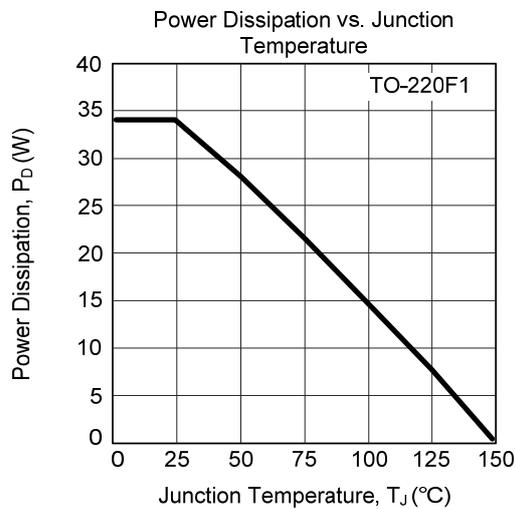
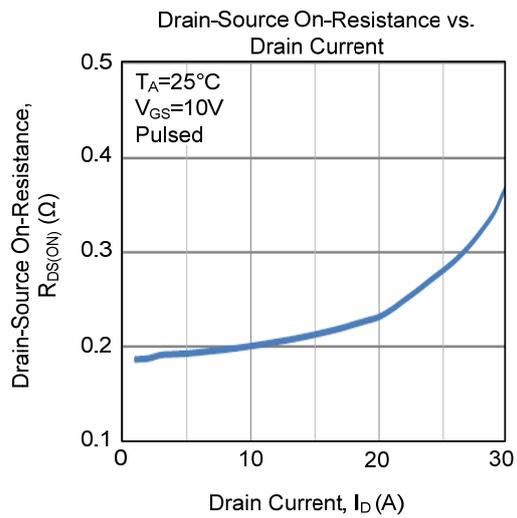
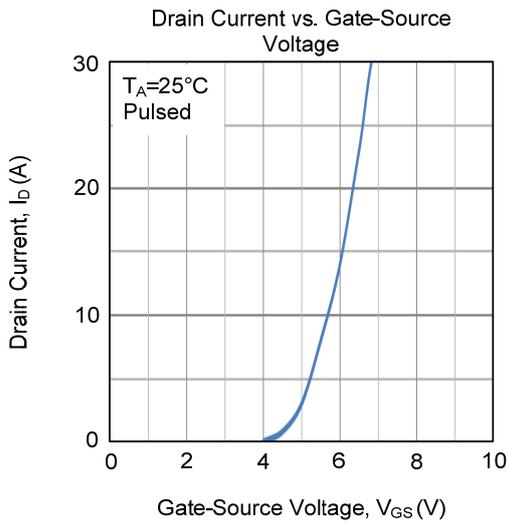
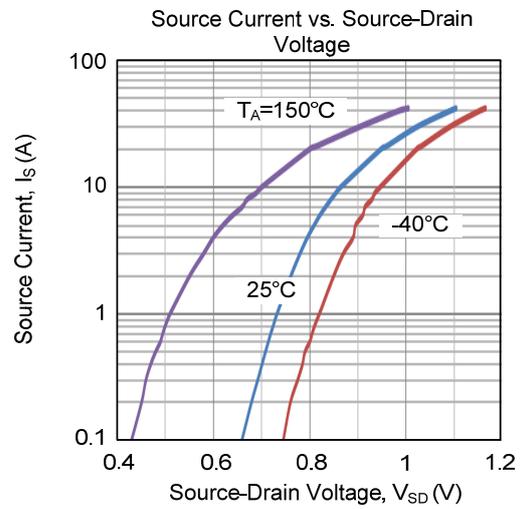
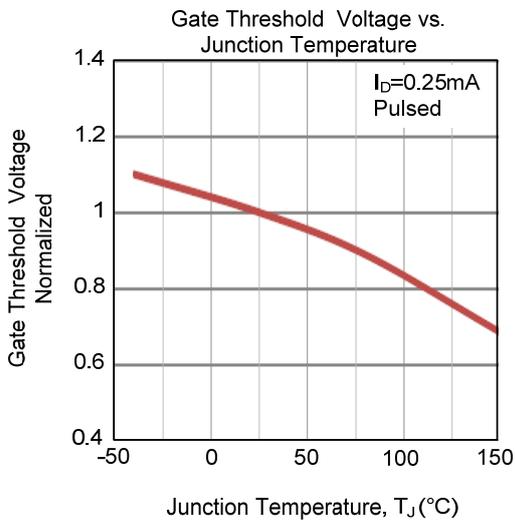
Unclamped Inductive Switching Waveforms



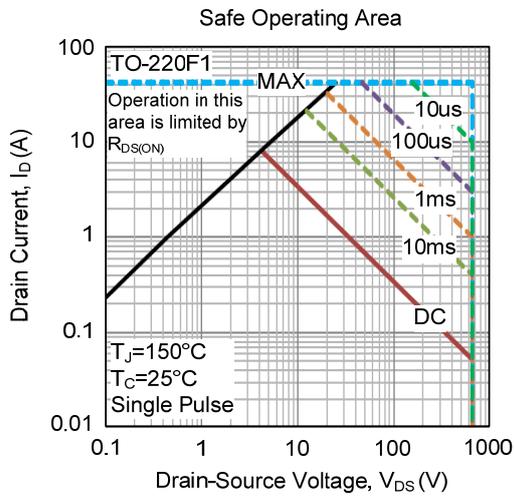
TYPICAL CHARACTERISTICS



■ TYPICAL CHARACTERISTICS (Cont.)



■ TYPICAL CHARACTERISTICS (Cont.)



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